

# Automotive Dual N-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY			
V <sub>DS</sub> (V)	60		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.064		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.082		
I <sub>D</sub> (A) per leg	5.4		
Configuration	Dual		

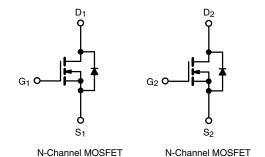
### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	SQ9945CEY (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	5.4		
	T <sub>C</sub> = 125 °C		3.1		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	3.6	Α	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	21.5		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	8.5		
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	3.6	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	D_	4	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	1.3	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount b	$R_{thJA}$	112	°C/W	
Junction-to-Foot (Drain)		$R_{thJF}$	38	G/ <b>VV</b>	

#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2	2.5		
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1		
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μA	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	20	-	-	Α	
Drain-Source On-State Resistance a		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.4 A	-	0.045	0.064		
	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.4 A, T <sub>J</sub> = 125 °C	-	-	0.110	Ω	
	$R_{DS(on)}$	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.4 A, T <sub>J</sub> = 175 °C	-	-	0.137		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 3.7 A	-	0.060	0.082	1	
Forward Transconductance f	9 <sub>fs</sub>	V <sub>DS</sub> :	= 15 V, I <sub>D</sub> = 3.7 A	-	12	-	S	
Dynamic <sup>b</sup>						•		
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	383	470	pF	
Output Capacitance	Coss	$V_{GS} = 0 V$		-	70	88		
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	33	37		
Total Gate Charge c	Qg		V <sub>DS</sub> = 30 V, I <sub>D</sub> = 4.3 A	-	8.9	12	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	1.5	1.7		
Gate-Drain Charge c	Q <sub>gd</sub>	1		-	2.1	2.6		
Gate Resistance	$R_g$	f = 1 MHz		1.1	-	6.66	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		$V_{DD}=30~V,~R_L=8.8~\Omega$ $I_D\cong 3.4~A,~V_{GEN}=10~V,~R_g=1~\Omega$		6	9	- ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =			2.8	4.2		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	I <sub>D</sub> ≅ 3.4 A,			17	26		
Fall Time <sup>c</sup>	t <sub>f</sub>				1.7	3		
Source-Drain Diode Ratings and Charact	eristics <sup>b</sup>					•		
Pulsed Current a	I <sub>SM</sub>			-	_	21.5	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V		-	0.75	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 1.7 A, di/dt = 100 A/μs			16	32	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>				13	26	nC	
Reverse recovery fall time	ta				13	-	ns	
Reverse recovery rise time	t <sub>b</sub>				3	-		
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>				-1.9	-	Α	

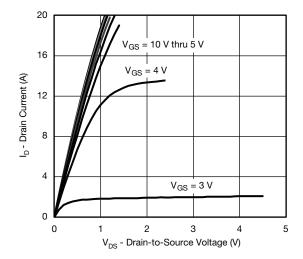
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

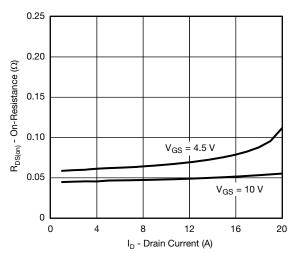
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



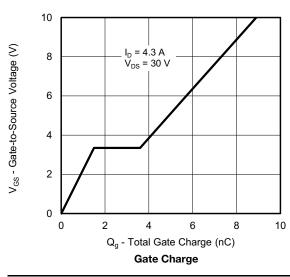
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

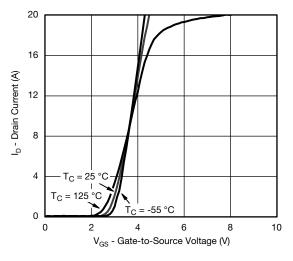


## **Output Characteristics**

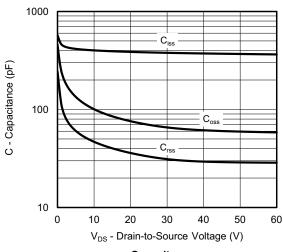


On-Resistance vs. Drain Current

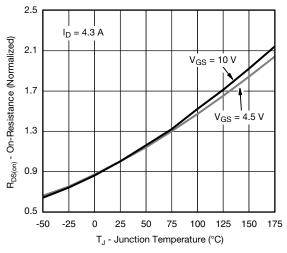




**Transfer Characteristics** 



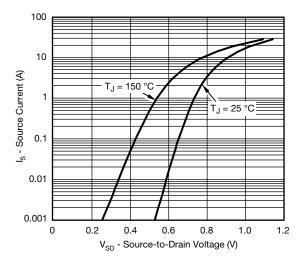
Capacitance



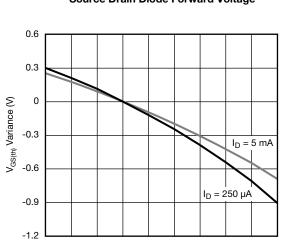
On-Resistance vs. Junction Temperature



## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



## **Source Drain Diode Forward Voltage**



**Threshold Voltage** 

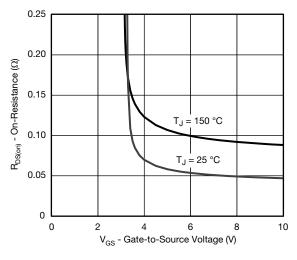
T<sub>.</sub> - Temperature (°C)

25 50

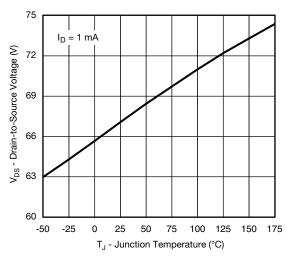
75 100

125

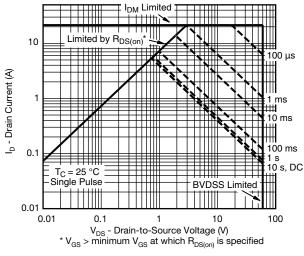
150 175



On-Resistance vs. Gate-to-Source Voltage



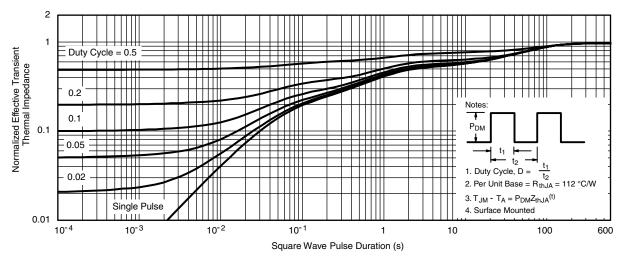
Drain Source Breakdown vs. Junction Temperature



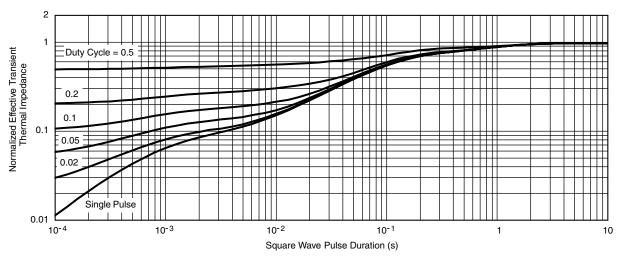
-50 -25 0



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



## Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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